



**Absolute Maximum Ratings (Cont.)** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Rating	Unit
$P_D$	Maximum Power Dissipation	$T_A=25^\circ\text{C}$	2.5
		$T_A=100^\circ\text{C}$	1.0
$T_J$	Maximum Junction Temperature	150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$R_{\theta JA}^*$	Thermal Resistance – Junction to Ambient	50	$^\circ\text{C/W}$

**Electrical Characteristics** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

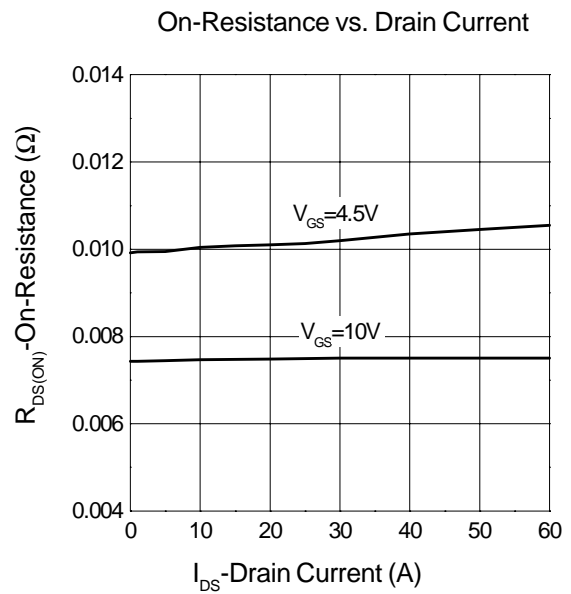
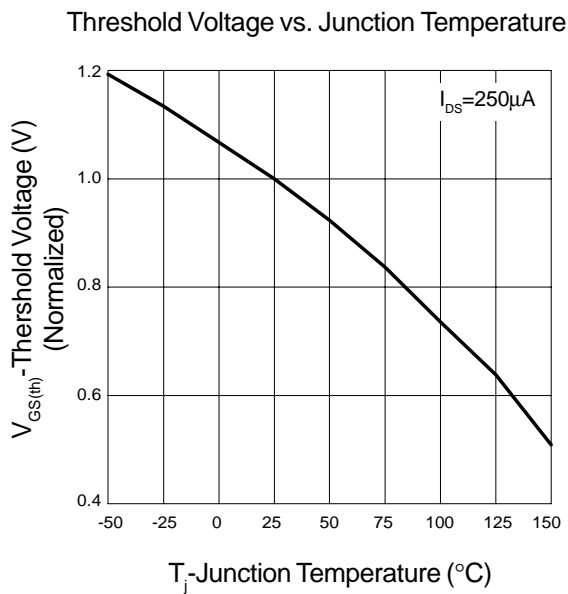
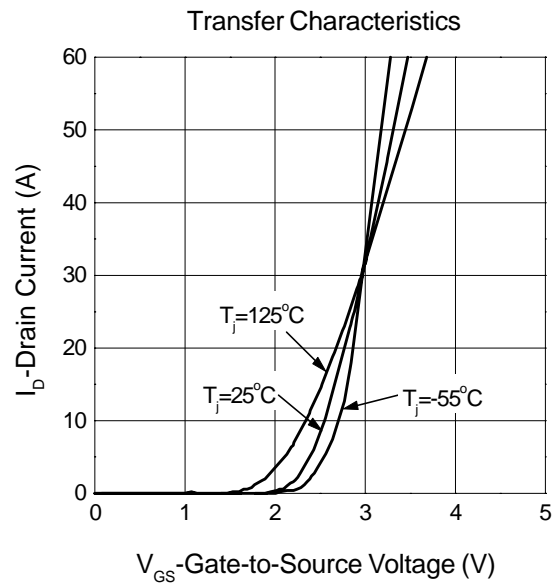
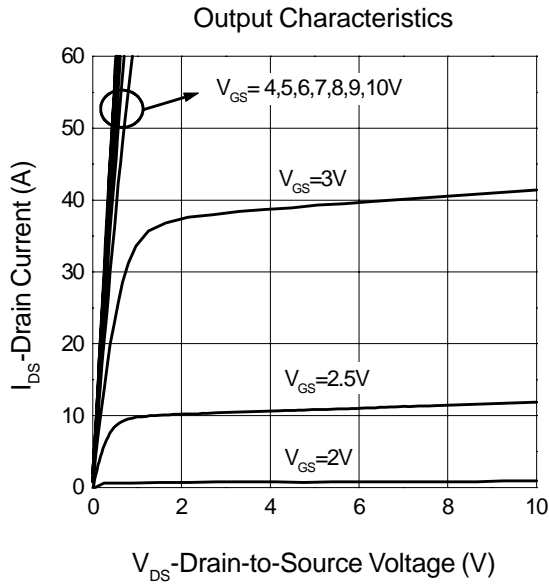
Symbol	Parameter	Test Condition	APM4220			Unit
			Min.	Typ.	Max.	
<b>Static</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=250\mu\text{A}$	25			V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=20V, V_{GS}=0V$			1	$\mu\text{A}$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=250\mu\text{A}$	1	1.5	2	V
$I_{GSS}$	Gate Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$			$\pm 100$	nA
$R_{DS(ON)}^a$	Drain-Source On-state Resistance	$V_{GS}=10V, I_{DS}=14A$		7.5	9	m $\Omega$
		$V_{GS}=4.5V, I_{DS}=8A$		10	12	
$V_{SD}^a$	Diode Forward Voltage	$I_S=16A, V_{GS}=0V$		0.7	1.2	V
<b>Dynamic<sup>b</sup></b>						
$Q_g$	Total Gate Charge	$V_{DS}=15V, I_{DS}=14A$ $V_{GS}=4.5V,$		16	20	nC
$Q_{gs}$	Gate-Source Charge			6		
$Q_{gd}$	Gate-Drain Charge			6		
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD}=15V, I_{DS}=1A,$ $V_{GEN}=10V, R_G=6\Omega,$		10	15	ns
$T_r$	Turn-on Rise Time			7	13	
$t_{d(OFF)}$	Turn-off Delay Time			35	50	
$T_f$	Turn-off Fall Time			10	20	
$C_{ISS}$	Input Capacitance	$V_{GS}=0V$		1785		pF
$C_{OSS}$	Output Capacitance	$V_{DS}=15V$		605		
$C_{RSS}$	Reverse Transfer Capacitance	Frequency=1.0MHz		490		

**Notes**

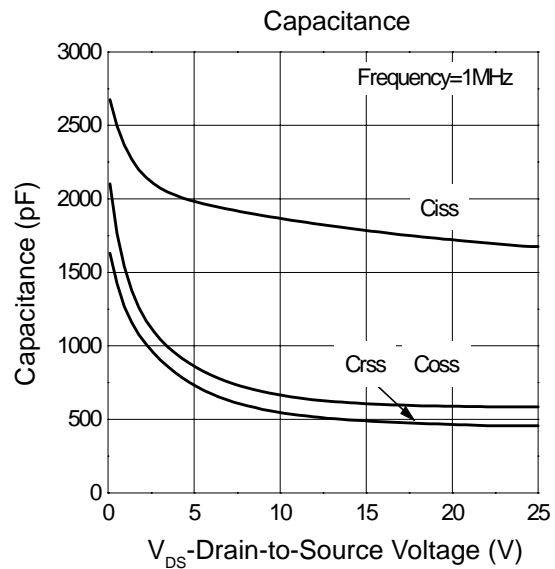
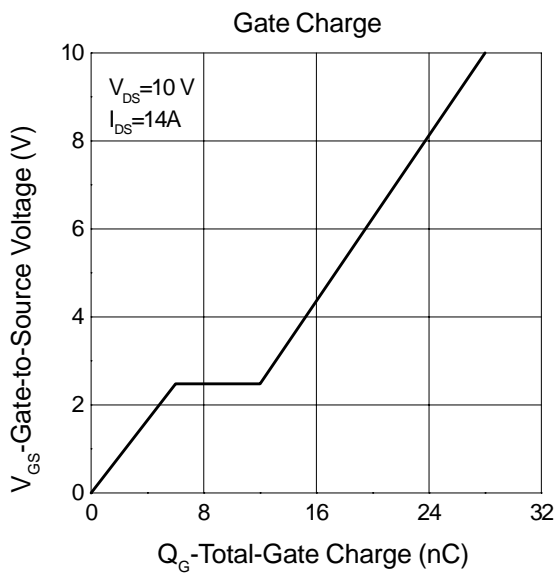
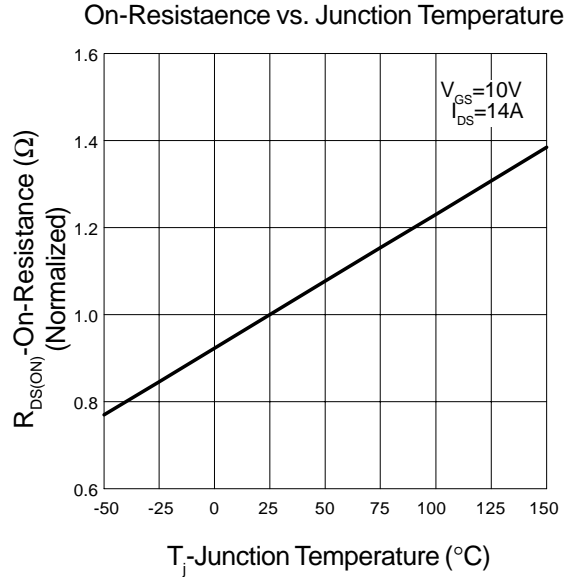
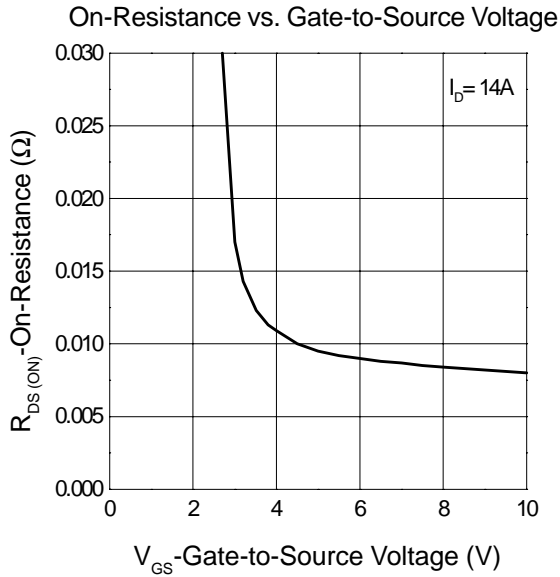
<sup>a</sup> : Guaranteed by design, not subject to production testing

<sup>b</sup> : Pulse test ; pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$

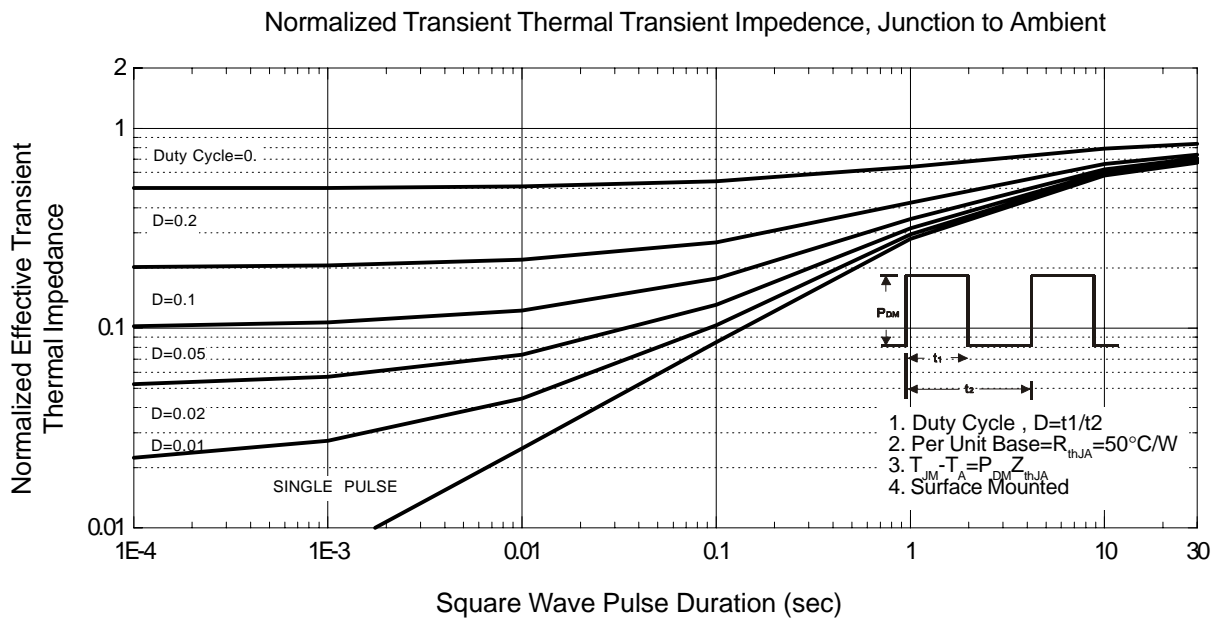
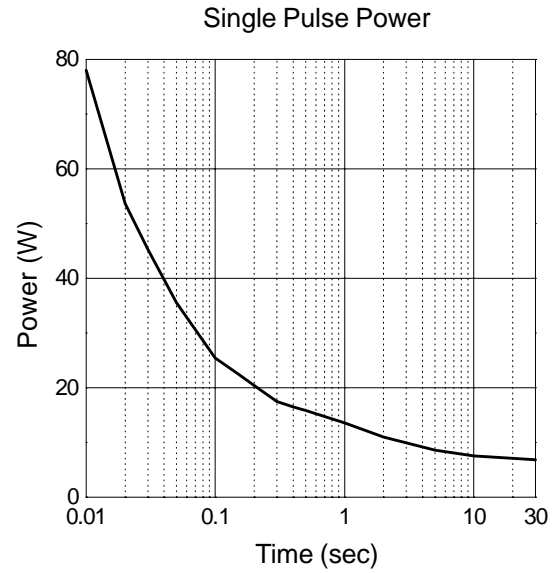
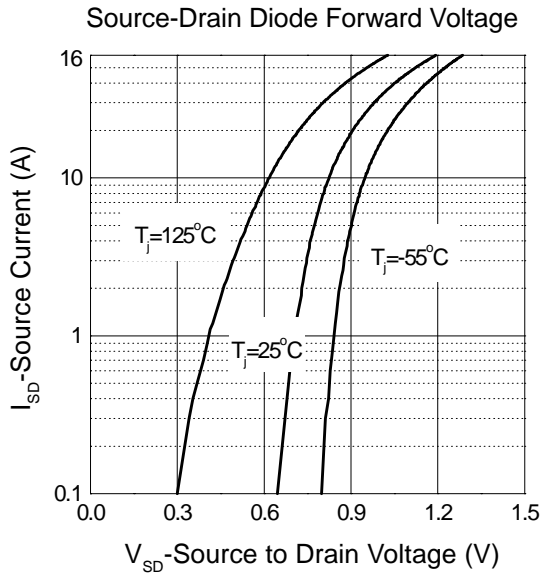
## Typical Characteristics



Typical Characteristics (Cont.)

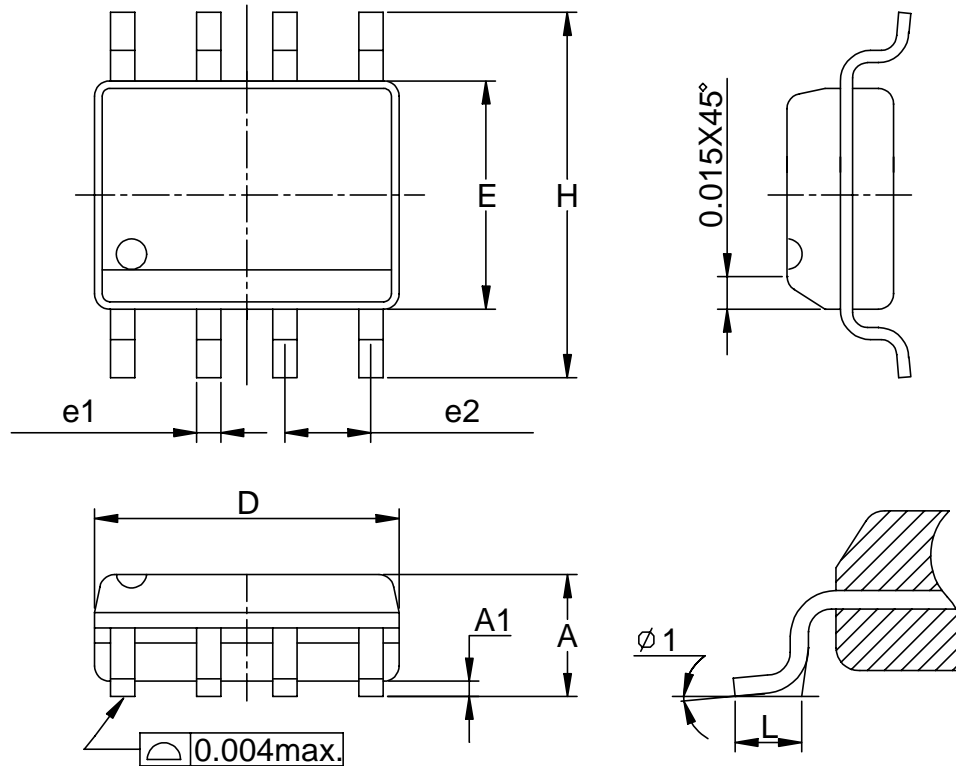


Typical Characteristics (Cont.)



## Packaging Information

SOP-8 pin ( Reference JEDEC Registration MS-012)



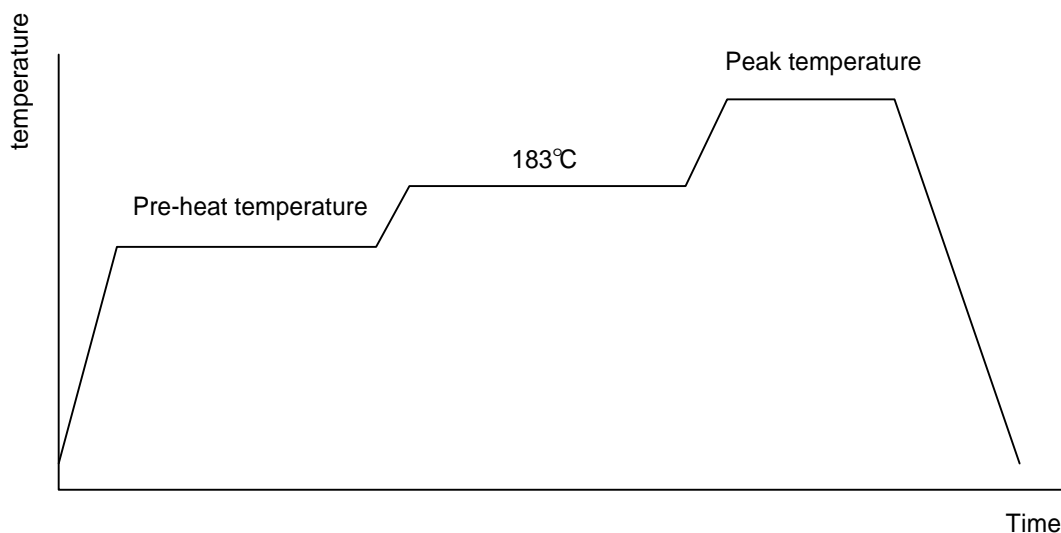
Dim	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.35	1.75	0.053	0.069
A1	0.10	0.25	0.004	0.010
D	4.80	5.00	0.189	0.197
E	3.80	4.00	0.150	0.157
H	5.80	6.20	0.228	0.244
L	0.40	1.27	0.016	0.050
e1	0.33	0.51	0.013	0.020
e2	1.27BSC		0.50BSC	
φ 1	8°		8°	

## Physical Specifications

Terminal Material	Solder-Plated Copper (Solder Material : 90/10 or 63/37 SnPb)
Lead Solderability	Meets EIA Specification RSI86-91, ANSI/J-STD-002 Category 3.

## Reflow Condition (IR/Convection or VPR Reflow)

Reference JEDEC Standard J-STD-020A APRIL 1999



## Classification Reflow Profiles

	Convection or IR/ Convection	VPR
Average ramp-up rate(183°C to Peak)	3°C/second max.	10 °C /second max.
Preheat temperature 125 ± 25°C)	120 seconds max	
Temperature maintained above 183°C	60 – 150 seconds	
Time within 5°C of actual peak temperature	10 –20 seconds	60 seconds
Peak temperature range	220 +5/-0°C or 235 +5/-0°C	215-219°C or 235 +5/-0°C
Ramp-down rate	6 °C /second max.	10 °C /second max.
Time 25°C to peak temperature	6 minutes max.	

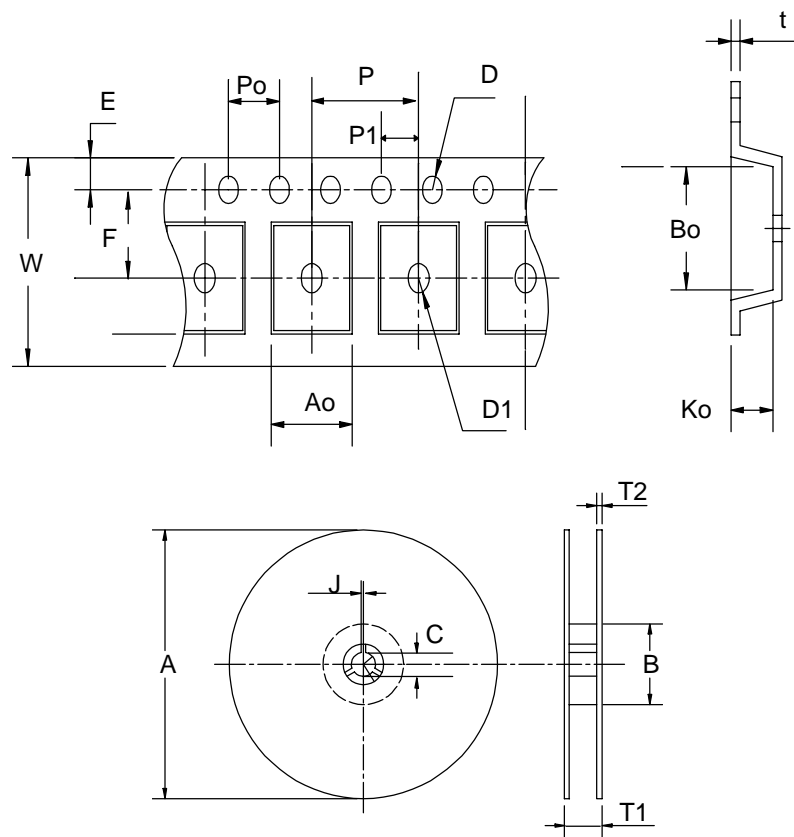
## Package Reflow Conditions

pkg. thickness ≥ 2.5mm and all bgas	pkg. thickness < 2.5mm and pkg. volume ≥ 350 mm <sup>3</sup>	pkg. thickness < 2.5mm and pkg. volume < 350mm <sup>3</sup>
Convection 220 +5/-0 °C		Convection 235 +5/-0 °C
VPR 215-219 °C		VPR 235 +5/-0 °C
IR/Convection 220 +5/-0 °C		IR/Convection 235 +5/-0 °C

## Reliability test program

Test item	Method	Description
SOLDERABILITY	MIL-STD-883D-2003	245°C, 5 SEC
HOLT	MIL-STD 883D-1005.7	1000 Hrs Bias @ 125°C
PCT	JESD-22-B, A102	168 Hrs, 100% RH, 121°C
TST	MIL-STD 883D-1011.9	-65°C ~ 150°C, 200 Cycles

## Carrier Tape & Reel Dimensions



<b>Application</b>	A	B	C	J	T1	T2	W	P	E
<b>SOP-8</b>	330±1	62 ± 1.5	12.75 + 0.15	2 + 0.5	12.4 +0.2	2± 0.2	12 + 0.3 - 0.1	8± 0.1	1.75± 0.1
<b>Application</b>	F	D	D1	Po	P1	Ao	Bo	Ko	t
<b>SOP-8</b>	5.5 ± 0.1	1.55±0.1	1.55+ 0.25	4.0 ± 0.1	2.0 ± 0.1	6.4 ± 0.1	5.2± 0.1	2.1± 0.1	0.3±0.013

(mm)



## Cover Tape Dimensions

Application	Carrier Width	Cover Tape Width	Devices Per Reel
SOP- 8	12	9.3	2500

## Customer Service

### **Anpec Electronics Corp.**

Head Office :

5F, No. 2 Li-Hsin Road, SBIP,

Hsin-Chu, Taiwan, R.O.C.

Tel : 886-3-5642000

Fax : 886-3-5642050

Taipei Branch :

7F, No. 137, Lane 235, Pac Chiao Rd.,

Hsin Tien City, Taipei Hsien, Taiwan, R. O. C.

Tel : 886-2-89191368

Fax : 886-2-89191369